

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Myung-Sun Kim	03/03/2009
Hwa-Sung Rhee	03/03/2009
Ho Lee	03/03/2009
Ji-Hye Yi	03/03/2009

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd.
Street Address:	416 Maetan-dong
Internal Address:	Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12419698

CORRESPONDENCE DATA

Fax Number: (919)854-1401
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: 919-854-1400
 Email: sfreedman@myersbigel.com
 Correspondent Name: Susan E. Freedman/MBSS
 Address Line 1: PO BOX 37428
 Address Line 4: RALEIGH, NORTH CAROLINA 27627

ATTORNEY DOCKET NUMBER:	5649-2513
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NAME OF SUBMITTER:	Susan E. Freedman
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Total Attachments: 5
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**PATENT
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ASSIGNMENT

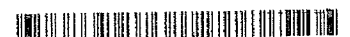
THIS ASSIGNMENT, made by us, **Myung-Sun Kim**, citizen of the Republic of Korea, residing at #608-1701, Hanwa Dream-green 2 Cha Apt., Bansong-dong, Hwaseong-si, Gyeonggi-do, Republic of Korea; **Hwa-Sung Rhee**, citizen of the Republic of Korea, residing at #106,402, Kkachi Maeul Daewoo Apt., Gumi-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Republic of Korea; **Ho Lee**, citizen of the Republic of Korea, residing at #105,904, Keangnam Honors Ville, Dujeong-dong, Seobuk-gu, Cheonan-si, Chungcheongnam-do, Republic of Korea; and **Ji-Hye Yi**, citizen of the Republic of Korea, residing at #116-602, Neulpureun Byoksan Apt., Mangpo-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea;

WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in **METHODS OF FABRICATING DIFFERENT THICKNESS SILICON-GERMANIUM LAYERS ON SEMICONDUCTOR INTEGRATED CIRCUIT DEVICES AND SEMICONDUCTOR INTEGRATED CIRCUIT DEVICES FABRICATED THEREBY**, for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. 12/419,698, filed 04/07/2009) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, **Samsung Electronics Co., Ltd.**, a Korean corporation having a principal place of business at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the



ASSIGNMENT – CONTINUED

term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

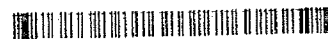
We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 3 day of March, 2009.

MyungSun Kim (SEAL)
Myung-Sun Kim

Witnessed by:

Date: _____



ASSIGNMENT – CONTINUED

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 2 day
of March, 2009.

HwaSung Rhee (SEAL)
Hwa-Sung Rhee

Witnessed by:

Date: _____



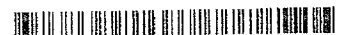
ASSIGNMENT - CONTINUED

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 3 day
of March, 2009.

Ho Lee (SEAL)
Ho Lee

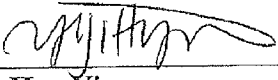
Witnessed by:

Date: _____



ASSIGNMENT – CONTINUED

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 3 day
of March, 2009.



Ji-Hye Yi (SEAL)

Witnessed by:

Date: _____

